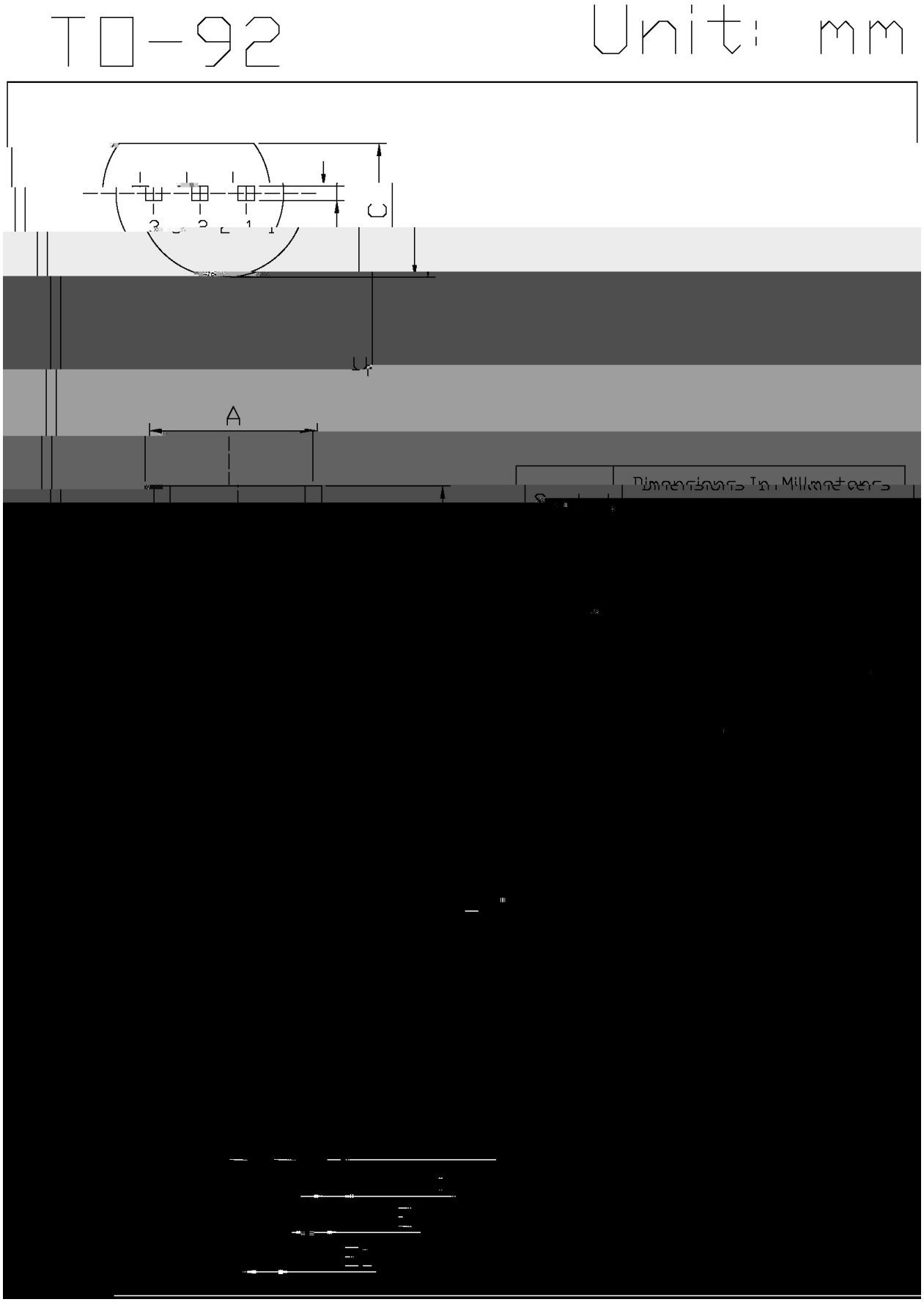
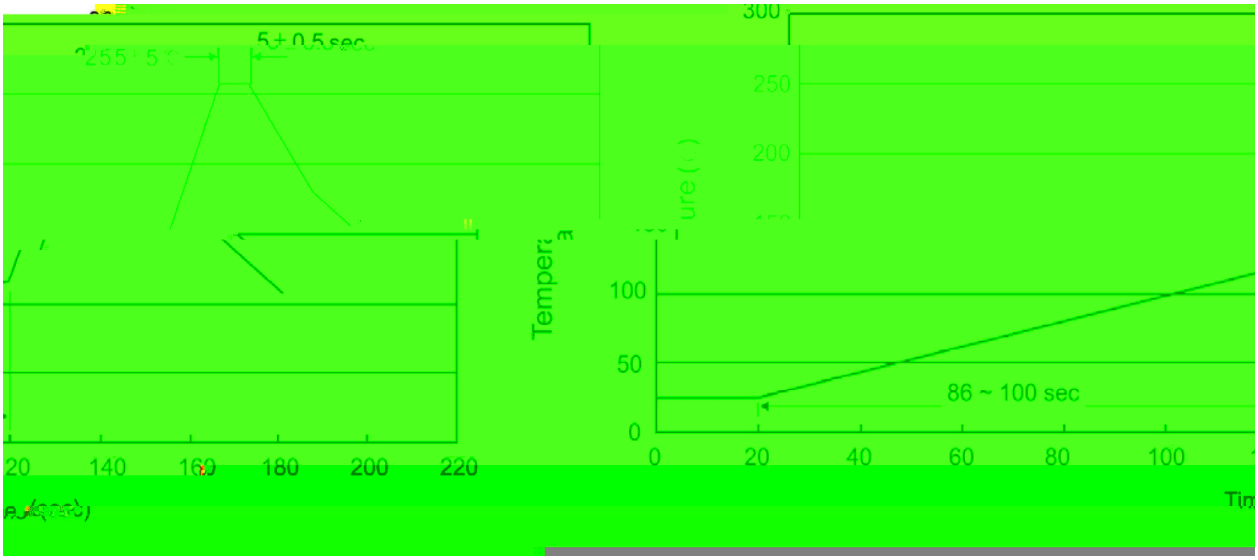
2SC2878

/ Package Dimensions



( ) / Temperature Profile for Dip Soldering(Pb-Free)



									Note:
1		25	150			60	90sec;		1.Preheating:25~150 , Time:60~90sec.
2		255±5					5±0.5sec;		2.Peak Temp.:255±5 , Duration:5±0.5sec.
3					2	10	/sec.		3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

270±5	10±1 sec.	Temp:270±5	Time:10±1 sec

/ Packaging SPEC.

/ BULK

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